

1.1 Scope.

This specification covers the detail requirement for a high speed, current feedback operational amplifier. It is highly recommended that this data sheet be used as a baseline for new military or aerospace specification control drawings.

1.2 Part Number.

The complete part numbers per Table 1 of this specification is as follows:

Device	Part Number	Package
-1	OP-160AZ/883	Z
-1	OP-160ARC/883	RC

1.2.3 Case Outline.

Letter Case Outline (Lead Finish Per MIL-M-38510)

- Z 8-Lead Ceramic Dual-in-Line Package (Cerdip)
 RC 20-Contact Leadless Chip Carrier (LCC)

1.3 Absolute Maximum Ratings. ($T_A = +25^\circ\text{C}$ unless otherwise noted)

Supply Voltage	$\pm 18 \text{ V}$
Input Voltage	Supply Voltage
Differential Input Voltage	$\pm 1 \text{ V}$
Inverting Input Current	$\pm 7 \text{ mA}$ Continuous $\pm 20 \text{ mA}$ Peak
Output Short-Circuit Duration	10 Seconds
Storage Temperature Range	$-65^\circ\text{C} \leq T_A \leq +150^\circ\text{C}$
Operating Temperature Range	$-55^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$
Lead Temperature Range (Soldering 60 sec)	$+300^\circ\text{C}$
Maximum Junction Temperature (T_J)	$+175^\circ\text{C}$

1.5 Thermal Characteristics.

Thermal Resistance, Cerdip (Z) Package:

- Junction-to-Case (θ_{JC}) = $16^\circ\text{C}/\text{W}$ max
 Junction-to-Ambient (θ_{JA}) = $148^\circ\text{C}/\text{W}$ max

Thermal Resistance, LCC (RC) Package:

- Junction-to-Case (θ_{JC}) = $38^\circ\text{C}/\text{W}$ max
 Junction-to-Ambient (θ_{JA}) = $98^\circ\text{C}/\text{W}$ max

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Table 1.

Test	Symbol	Device Types	Limits Min	Limits Max	Group A Subgroups	Test Condition ¹	Units
Input Offset Voltage ²	V _{OS}	-1		±5	1	T _A = +25°C	mV
				±8	2, 3	T _A = -55°C, +125°C	
Noninverting Input Bias Current	I _{B+}	-1		±1	1	T _A = +25°C	μA
				±2	2, 3	T _A = -55°C, +125°C	
Inverting Input Bias Current	I _{B-}	-1		±20	1	T _A = +25°C	μA
				±30	2, 3	T _A = -55°C, +125°C	
Noninverting Input Bias Current Common-Mode Rejection Ratio	CMRRI _{B+}	-1		75	1	V _{CM} = ±11 V; T _A = +25°C	nA/V
				150	2, 3	V _{CM} = ±10 V; T _A = -55°C, +125°C	
Inverting Input Bias Current Common-Mode Rejection Ratio	CMRRI _{B-}	-1		75	1	V _{CM} = ±11 V; T _A = +25°C	nA/V
				150	2, 3	V _{CM} = ±10 V; T _A = -55°C, +125°C	
Noninverting Input Bias Current Power Supply Rejection Ratio	PSRRI _{B+}	-1		5	1	V _S = ±9 V, ±18 V; T _A = +25°C	nA/V
				10	2, 3	V _S = ±9 V, ±18 V; T _A = -55°C, +125°C	
Inverting Input Bias Current Power Supply Rejection Ratio	PSRRI _{B-}	-1		50	1	V _S = ±9 V, ±18 V; T _A = +25°C	nA/V
				100	2, 3	V _S = ±9 V, ±18 V; T _A = -55°C, +125°C	
Common-Mode Rejection	CMR	-1	60		1	V _{CM} = ±11 V; T _A = +25°C	dB
			56		2, 3	V _{CM} = ±10 V; T _A = -55°C, +125°C	
Power Supply Rejection	PSR	-1	74		1	V _S = ±9 V, ±18 V; T _A = +25°C	dB
			70		2, 3	V _S = ±9 V, ±18 V; T _A = -55°C, +125°C	
Input Voltage Range ³	IVR	-1	±11		1	T _A = +25°C	V
			±10		2, 3	T _A = -55°C, +125°C	
Output Voltage Swing	V _O	-1	±11		4	R _L = 500 Ω; T _A = +25°C	V
			±10		5, 6	R _L = 500 Ω; T _A = -55°C, +125°C	
Output Current	I _O	-1	±35		4	V _O = ±10 V; T _A = +25°C	mA
Transimpedance	R _T	-1	3		4	V _O = ±10 V; R _L = 500 Ω; T _A = +25°C	MΩ
			1.75		5, 6	V _O = ±10 V; R _L = 500 Ω; V _O = ±10 V; T _A = -55°C, +125°C	
Slew Rate	SR	-1	1000		7	A _V = +2, R _L = 500 Ω; T _A = +25°C V _O = ±10 V, Test at V _O = ±5 V	V/μs
Supply Current	I _{SY}	-1		8	1	No Load, T _A = +25°C	mA
				9	2, 3	No Load; T _A = -55°C, +125°C	

NOTES

¹V_S = ±15 V, V_{CM} = 0 V, R_F = 820 Ω; unless otherwise specified.

²The input offset voltage (V_{OS}) and inverting bias current can be adjusted with an external 10 kΩ potentiometer between the NULL pins with wiper connected to V₊ to make output offset voltage zero.

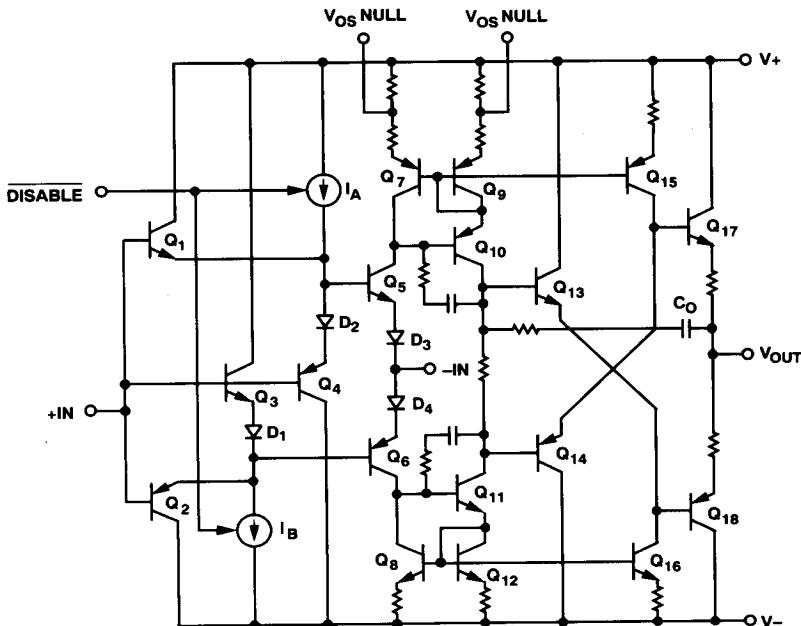
³Input voltage range (IVR) guaranteed by common-mode rejection (CMR) test.

Table 2. Electrical Test Requirements

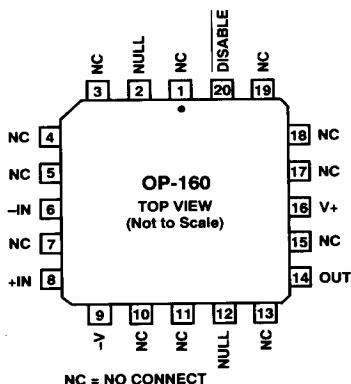
MIL-STD-883 Test Requirements	Subgroups (See Table 1)
Interim Electrical Parameters (Pre-Burn-In)	1
Final Electrical Test Parameters	1, * 2, 3, 4, 5, 6
Group A Test Requirements	1, 2, 3, 4, 5, 6, 7

*PDA applies to Subgroup 1 only. No other subgroups are included in PDA.

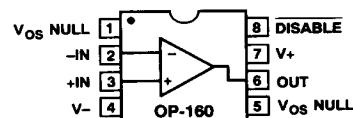
3.2.1 Functional Block Diagram and Terminal Assignments.



20-Position LCC
(RC Suffix)



8-Pin Ceramic DIP
(Z Suffix)



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3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group (49).

4.2.1 Life Test/Burn-In Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in performed per MIL-STD-883 Method 1015 test condition (C).

